

Bill of Materials

TI DESIGNS

PMP10681

ltem	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	RoHS
1	1	AA1		Printed Circuit Board	TBD			0
2	5	C1, C2, C3, C4, C5	2.2uF	CAP, CERM, 2.2uF, 100V, +/-20%, X7R, 1812	TDK	C4532X7R2A225M	1812	Υ
3	1	C6	0.1uF	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0805	Kemet	C0805C104K1RACTU	0805	Υ
4	2	C7, C20	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0805	MuRata	GRM219R71E105KA88D	0805	Υ
5	3	C8, C16, C21	0.1uF	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	MuRata	GRM188R72A104KA35D	0603	Υ
6	2	C9, C10	47uF	CAP, CERM, 47uF, 16V, +/-10%, X5R, 1210	MuRata	GRM32ER61C476KE15L	1210	Υ
7	2	C11, C12	0.47uF	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 1206	AVX	12063C474KAT2A	1206	Υ
8	2	C13, C14	180uF	CAP, AL, 180uF, 16V, +/-20%, 0.026 ohm, SMD	Nippon Chemi-Con	APXH160ARA181MJ80G	SMD	Υ
9	1	C15	220pF	CAP, CERM, 220 pF, 50 V, +/- 10%, X7R, 0603	MuRata	GRM188R71H221KA01D	0603	Υ
10	1	C17	1200pF	CAP, CERM, 1200 pF, 50 V, +/- 10%, X7R, 0603	MuRata	GRM188R71H122KA01D	0603	Y
11	1	C18	0.039uF	CAP, CERM, 0.039 µF, 25 V, +/- 10%, X7R, 0603	MuRata	GRM188R71E393KA01D	0603	Υ
12	1	D1		Diode, Schottky, 35V, 10A, DPAK	ON Semiconductor	MBRD1035CTLT4G	DPAK	Y
13	1	D4		Diode, Schottky, 100V, 20A, DDPAK	Vishay	VB40100C-E3/4W	DDPAK	Υ
14	3	FID1, FID2, FID3		Fiducial mark. There is nothing to buy or mount.	N/A	N/A		Υ
15	4	H1, H2, H3, H4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH		Υ
16	4	H5, H6, H7, H8		Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C		Υ
17	4	J1, J2, J3, J4		Terminal, Turret, TH, Double	Keystone	1503-2		Υ
18	1	L1		Inductor, Shielded Drum Core, Mn-Zn, 7 µH, 21 A, 0.005608 ohm, SMD	Wurth Elektronik	7443630700	SMD	Υ
19	2	Q1, Q2		MOSFET, N-CH, 75V, 12A, PowerPAK SO-8	Vishay-Siliconix	SI7148DP	SO-8	Υ
20	1	R1	75k ohm	RES, 75.0k ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW080575K0FKEA	0805	Υ
21	1	R2	1M ohm	RES, 1.00Meg ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW08051M00FKEA	0805	Υ
22	1	R3	64.9k ohm	RES, 64.9 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-0764K9L	0603	Υ
23	1	R4	13k ohm	RES, 13.0 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060313K0FKEA	0603	Υ
24	1	R5	0 ohm	RES, 0 ohm, 5%, 0.125W, 0805	Vishay-Dale	CRCW08050000Z0EA	0805	Υ
25	1	R7	22.1k ohm	RES, 22.1 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060322K1FKEA	0603	Υ
26	1	R8	5.6k ohm	RES, 5.60 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-075K6L	0603	Υ
27	1	R9	1.8k ohm	RES, 1.80 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-071K8L	0603	Υ
28	1	R10	0 ohm	RES, 0 ohm, 5%, 0.25W, 1206	Vishay-Dale	CRCW12060000Z0EA	1206	Υ
29	1	R11	0 ohm	RES, 0 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06030000Z0EA	0603	Υ
30	1	R12	10 ohm	RES, 10.0 ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060310R0FKEA	0603	Υ
31	1	R13	0.015 ohm	RES, 0.015 ohm, 1%, 2W, 3008	Susumu Co Ltd	RL7520WT-R015-G	3008	Υ
32	2	TP1, TP9		Test Point, TH, Multipurpose, Black	Keystone	5011		Υ
33	1	TP2		Test Point, TH, Multipurpose, Red	Keystone	5010		Υ

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34	1	TP3		Test Point, TH, Multipurpose, Blue	Keystone	5127		Υ
35	1	TP4		Test Point, TH, Multipurpose, Orange	Keystone	5013		Υ
36	2	TP7, TP8		Test Point, TH, Multipurpose, White	Keystone	5012		Υ
	1	U1		Wide Voltage Range Buck-Boost Controller, 20-pin TSSOP-EP, Pb-	Texas Instruments	LM5118MH/NOPB		
37				Free			TSSOP	Υ
38	0	C19, C22, R6		DNP				Υ
39	0	D5		Diode, Schottky, 100V, 0.2A, SOD-123	ST Microelectronics	BAT41ZFILM	SOD-123	Y

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